

REMARKS

At the outset, the Examiner is thanked for the thorough review and consideration of the pending application. The Office Action dated April 11, 2005, has been received and its contents carefully reviewed.

Claims 1-8 are withdrawn in this application. Claims 9-26 are rejected to by the Examiner. Claim 9 has been amended, and claims 23-26 have been canceled. Claims 9-22 remain pending in this application.

Claims 9-13, 18, 19, 21, and 22 are rejected under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent Publication No. 2002/0004108 to Iwakabe et al. (hereinafter "Iwakabe"). Claims 23-26 are rejected under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 5,978,058 to Sung (hereinafter "Sung"). Claims 14-17, and 20 are rejected under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent Publication No. 2002/0004108 to Iwakabe et al. (hereinafter "Iwakabe") as applied to claims 9-13, 18, 19, 21, and 22 above in view of U.S. Patent No. 6,268,289 to Chowdhury (hereinafter "Chowdhury").

The rejection of claims 9-22 is respectfully traversed and reconsideration is requested. Claims 9-22 are allowable over the cited references in that each of these claims recites a combination of elements including, for example, "forming a silicide layer on the metal line in direct contact with at least a first surface portion of the metal line". None of the cited references including Iwakabe et al., Sung or Chowdhury, singly or in combination, teaches or suggests at least this feature of the claimed invention.

Iwakabe et al. teaches the silicide layer SD1(d1) is on and in contact with the gate insulating film GI, which is in between the silicide layer SD(d1) and the gate electrode GT (g1). This is in opposition to the claimed invention which includes "a silicide layer on the metal line in direct contact with at least a first surface portion of the metal line." In Iwakabe the silicide layer SD (d1) is not in direct contact with the gate electrode GT (g1). Further, neither Sung nor Chowdhury overcome this deficiency of Iwakabe. Accordingly, Applicants respectfully submit that claims 9-22 are allowable over the cited references.


Applicants believe the foregoing amendments place the application in condition for allowance and early, favorable action is respectfully solicited.

If for any reason the Examiner finds the application other than in condition for allowance, the Examiner is requested to call the undersigned attorney at (202) 496-7500 to discuss the steps necessary for placing the application in condition for allowance. All correspondence should continue to be sent to the below-listed address.

If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. § 1.136, and any additional fees required under 37 C.F.R. § 1.136 for any necessary extension of time, or any other fees required to complete the filing of this response, may be charged to Deposit Account No. 50-0911. Please credit any overpayment to deposit Account No. 50-0911. *A duplicate copy of this sheet is enclosed.*

Respectfully submitted,

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By 
Eric J. Nuss
Registration No. 40,106

McKENNA LONG & ALDRIDGE LLP
1900 K Street, N.W.
Washington, DC 20006
(202) 496-7500
Attorneys for Applicant

Attachments